

ABSTRACT OF THE DISCLOSURE

To suppress enlargement of the chip size, and improve the reliability in interlayer connections. Grooves 4a – 4c are provided at positions of scribe lines SL of semiconductor substrates 1a – 1c; and conductive material 11 is filled in the grooves 4a – 4c provided in sections of the semiconductor substrates 1a – 1c after the semiconductor substrates 1a – 1c are stacked in layers.